

Temperature and Power Supply System Monitors

Check for Samples: [TMP512](http://focus.ti.com/docs/prod/folders/print/tmp512.html#samples), [TMP513](http://focus.ti.com/docs/prod/folders/print/tmp513.html#samples)

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- **AVERAGING**
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- **HIGH ACCURACY: 1% MAX OVER TEMP**
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- **INDUSTRIAL CONTROLLERS**
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- **LCD/DLP®/LCOS PROJECTORS**
- **STORAGE AREA NETWORKS (SAN)** +125°C.

¹FEATURES DESCRIPTION

²³⁴ The TMP512 (dual-channel) and TMP513 • ±**1**°**C REMOTE DIODE SENSORS** (triple-channel) are system monitors that include • [±]**1**°**^C LOCAL TEMPERATURE SENSOR** remote sensors, ^a local temperature sensor, and ^a high-side current shunt monitor. These system • **n-FACTOR CORRECTION** monitors have the capability of measuring remote temperatures, on-chip temperatures, and system • **TEMPERATURE ALERT FUNCTION** voltage/power/current consumption.

The remote temperature sensor diode-connected **12-BIT RESOLUTION**
 12-BIT RESOLUTION
 12-BIT RESOLUTION
 12-BIT RESOLUTION
 12-BIT RESOLUTION
 12-BIT RESOLUTION
 12-BIT RESOLUTION transistors or diodes that are an integral part of **SENSES BUS VOLTAGES FROM 0V TO +26V** microcontrollers, microprocessors, or FPGAs.
REPORTS CURRENT IN AMPS VOLTAGE IN Remote accuracy is ±1°C for multiple IC REPORTS CURRENT IN AMPS, VOLTAGE IN

VOLTS AND POWER IN WATTS

HIGH ACCURACY: 1% MAX OVER TEMP two-wire serial interface accepts SMBusTM or

HIGH ACCURACY: 1% MAX OVER TEMP two-wire write and read commands.

WATCHDOG LIMITS: The onboard current shunt monitor is a high-side – **Upper Over-Limit** current shunt and power monitor. It monitors both the shunt drop and supply voltage. A programmable – **Lower Under-Limit** calibration value (along with the TMP512/TMP513 internal digital multiplier) enables direct readout in **APPLICATIONS** amps; an additional multiplication calculates power in • **DESKTOP AND NOTEBOOK COMPUTERS** watts. The TMP512 and TMP513 both feature two separate onboard watchdog capabilities: an over-limit • **SERVERS** comparator and a lower-limit comparator.

These devices use a single +3V to +26V supply, • **CENTRAL OFFICE TELECOM EQUIPMENT** drawing a maximum of 1.4mA of supply current, and they are specified for operation from -40° C to

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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE INFORMATION(1)

(1) For the most current package and ordering information see the Package Option Addendum at the end of this document, or visit the [TMP512/TMP513](http://focus.ti.com/docs/prod/folders/print/tmp513.html) product folder at www.ti.com.

ABSOLUTE MAXIMUM RATINGS(1)

Over operating free-air temperature range (unless otherwise noted).

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) V_{IN+} and V_{IN-} may have a differential voltage of -26V to +26V; however, the voltage at these pins must not exceed the range -0.3V to +26V.

THERMAL INFORMATION

(1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, [SPRA953](http://www.ti.com/lit/pdf/spra953).

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ELECTRICAL CHARACTERISTICS: V+ = +12V

Boldface limits apply over the specified temperature range, **T^A =** –**40**°**C to +125**°**C.**

At T_A = +25°C, V+ = 12V, V_{SENSE} = (V_{IN+} – V_{IN-}) = 32mV, PGA = ÷ 1, and BRNG⁽¹⁾ = 1, unless otherwise noted.

(1) BRNG is bit 13 of [Configuration](#page-32-0) Register 1.

(2) This parameter only expresses the full-scale range of the ADC scaling. In no event should more than 26V be applied to this device.

(3) Referred-to-input (RTI).

(4) See [Subregulator](#page-12-0) section.

ELECTRICAL CHARACTERISTICS: V+ = +12V (continued)

Boldface limits apply over the specified temperature range, **T^A =** –**40**°**C to +125**°**C.**

At T_A = +25°C, V+ = 12V, V_{SENSE} = (V_{IN+} – V_{IN-}) = 32mV, PGA = ÷ 1, and BRNG^{[\(1\)](#page-4-0)} = 1, unless otherwise noted.

(5) Tested with one-shot measurements, and with less than 5Ω effective series resistance, and with 100pF differential input capacitance.
(6) See Subregulator section.

See [Subregulator](#page-12-0) section.

(7) SMBus timeout in the TMP512/13 resets the interface any time SCL or SDA is low for over 28ms.

[TMP512](http://focus.ti.com/docs/prod/folders/print/tmp512.html) [TMP513](http://focus.ti.com/docs/prod/folders/print/tmp513.html)

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Texas INSTRUMENTS

PIN CONFIGURATIONS

TMP512

TMP512: PIN DESCRIPTIONS

TMP513

TMP513: PIN DESCRIPTIONS

EXAS ISTRUMENTS

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TYPICAL CHARACTERISTICS: V+ = +12V (continued)

(VIN+ at 12V, Sweep of VIN–**) ACTIVE I^Q vs TEMPERATURE**

EXAS **STRUMENTS**

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REMOTE TEMPERATURE ERROR vs DIFFERENTIAL CAPACITANCE

[TMP512](http://focus.ti.com/docs/prod/folders/print/tmp512.html) [TMP513](http://focus.ti.com/docs/prod/folders/print/tmp513.html)

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PARAMETRIC MEASUREMENT INFORMATION

TYPICAL CONNECTIONS

Figure 18. SERIES RESISTANCE CONFIGURATION

(1) R_{S1} + R_{S2} should be less than 1kΩ; see *[Filtering](#page-19-0)* section.

Figure 19.

Figure 20. DIFFERENTIAL CAPACITANCE CONFIGURATION

(a) GND Collector-Connected Transistor

(b) Diode-Connected Transistor

(1) C_{DIFF} should be less than 2200pF; see *[Filtering](#page-19-0)* section.

APPLICATION INFORMATION

The TMP512/13 are digital temperature sensors with the bust of the bus. SDA is an open-drain The addigital current-shunt monitor that combine a local a digital current-shunt monitor that combine a local circuit.
die temperature measurement channel and remote junction temperature measurement channels: two for
the TMP512 and three for the TMP513. The
TMP512/13 contain multiple registers for holding The subregulator can be configured to three different TMP512/13 contain multiple registers for holding configuration information, temperature, and voltage modes of operation. Each mode has its advantage measurement results. These devices provide digital and limitation. [Figure](#page-12-1) 22 shows the three current, voltage, and power readings necessary for configuration arrangements. The minimum accurate decision-making in precisely-controlled capacitance on the Filter C pin for Configurations 1 systems. Programmable registers allow flexible and 2 is 470nF. The minimum capacitance on the configuration for setting warning limits, measurement Filter C pin for Configuration 3 is 100nF. configuration for setting warning limits, measurement resolution, and continuous-versus-triggered
operation. Detailed register information appears at configuration 1 has V+ and V_{IN+} tied together. V+
the end of this data sheet, beginning with [Table](#page-31-0) 3.
supplies the subregu

For proper remote temperature sensing operation, the V+ supply range of 4.5V to 26V connected to the TMP512 requires transistors connected between shunt voltage, the bus voltage range cannot go to
DXP1 and DXN1 and between DXP2 and DXN2, and zero and is limited to 4.5V to 26V. DXP1 and DXN1 and between DXP2 and DXN2, and for the TMP513, between DXP3 and DXN3 as well.

Unused channels on the TMP512/13 must be any other connections. Under this configuration, the connected to GND.

The TMP512/13 offer compatibility with two-wire and is not limited to 4.5V as in Configuration 1. SMBus interfaces. The two-wire and SMBus
protocols are essentially compatible with each other.
Two-wire is used throughout this data sheet, with
SMBus being specified only when a difference
state of this voltage range. The

between the two systems is being addressed. Two **DESCRIPTION** bi-directional lines, SCL and SDA, connect the business of the state of the TMP512/13 to the business SDA is an open-drain

3.3V to the Filter C pin and the internal die. With the

bus voltage range can go from 0V to 26V, because it

range can go from 0V to 26V, because it is not limited to 4.5V as in Configuration 1.

Figure 22. Typical Subregulator Configurations

orientise result in a temperature onset. A total of up
to 3kΩ of series line resistance is cancelled by the
TMP512/13, eliminating the need for additional
characterization and temperature offset correction.
See the Remot for details on the effects of series resistance and complete. Only power-supply voltage on sensed remote temperature error. **REGISTER INFORMATION**

temperature error. The effect of capacitance on sensed remote temperature error is illustrated in sensed remote temperature error is illustrated in **POINTER REGISTER** [Figure](#page-10-0) 16, Remote Temperature Error vs Differential Capacitance. See the *[Filtering](#page-19-0)* section for suggested The 8-bit Pointer Register is used to address a given component values where filtering unwanted coupled data register. The Pointer Register identifies which of component values where filtering unwanted coupled data register. The Pointer Register identifies which of signals is needed.

The Temperature Register of the TMP512/13 is configured as a 13-bit, read-only register that stores the output of the most recent conversion. Two bytes must be read to obtain data, and are described in the

SERIES RESISTANCE CANCELLATION Local [Temperature](#page-43-0) Result Register and the [Remote](#page-44-0)
 Call Temperature Result Registers Note that byte 1 is the Series resistance in an application circuit that typically
results from printed circuit board (PCB) trace
resistance and remote line length is automatically
cancelled by the TMP512/13, preventing what would
otherwise resul

DIFFERENTIAL INPUT CAPACITANCE The TMP512/13 contain multiple registers for holding The TMP512/13 can tolerate differential input
capacitance of up to 2200pF with minimal change in easurement results, and status information. These
registers are described in [Table](#page-31-0) 3.

the data registers should respond to a read or write command on the two-wire bus. This register is set **TEMPERATURE MEASUREMENT DATA** with every write command. A write command must be Temperature measurement data may be taken over
an operating range of -40°C to +125°C for both local
the pointer edgree of the TMD512/13 registers. The an operating range of -40 C to +125°C for both local the pointer address of the TMP512/13 registers. The and remote locations.
power-on reset (POR) value of the Pointer Register is
The Temperature Register of the TMP512

uses sequential current excitation to extract a differential V_{BE} voltage measurement to determine
thus having no effect unless the register is written to.
the temperature of the remote transistor. [Equation](#page-14-1) 1 describes this voltage and temperature. **BUS OVERVIEW**

$$
V_{BE2} - V_{BE1} = \frac{n k T}{q} \ln \left(\frac{I_2}{I_1} \right)
$$
 (1)

particular transistor used for the remote channel. The device that generates the serial clock (SCL), controls power-on reset value for the TMP512/13 is $n = 1,008$ the bus access, and generates START and STOP power-on reset value for the TMP512/13 is $n = 1.008$. the bus access of the bus and The value in the p Easter Correction Begister may be The value in the n-Factor Correction Register may be used to adjust the effective n-factor according to To address a specific device, the master initiates a
Equation 2 and Equation 3. START condition by pulling the data signal line (SDA)

$$
n_{\text{eff}} = \frac{1.008 \times 300}{(300 - N_{\text{ADJUST}})}
$$
(2)

$$
N_{ADJUST} = 300 - \left(\frac{300 \times 1.008}{n_{eff}}\right)
$$
 (3)

n-FACTOR CORRECTION REGISTER twos-complement format, yielding an effective data
The TMDE12/12 ellow for a different a fector value to range from -128 to +127. The n-factor value may be The TMP512/13 allow for a different n-factor value to
be used for converting remote channel
measurements to temperature. The remote channel
measurements to temperature. The remote channel
channel 2, and pointer address 18h

The device that initiates the transfer is called a master, and the devices controlled by the master are The value n in [Equation](#page-14-1) 1 is a characteristic of the slaves. The bus must be controlled by a master

> START condition by pulling the data signal line (SDA) from a HIGH to a LOW logic level while SCL is HIGH. All slaves on the bus shift in the slave address byte on the rising edge of SCL, with the last bit indicating whether a read or write operation is intended. During the ninth clock pulse, the slave being addressed
responds to the master by generating an in Acknowledge and pulling SDA LOW.

Figure 23. Typical Application Circuit

Data transfer is then initiated and eight bits of data **WRITING TO/READING FROM THE** are sent, followed by an Acknowledge bit. During data transfer, SDA must remain stable while SCL is

Once all data have been transferred, the master registers and corresponding addresses. The value for generates a STOP condition, indicated by pulling the register pointer as shown in [Figure](#page-17-0) 26 is the first SDA from LOW to HIGH while SCL is HIGH. The byte transferred after the slave address byte with the SDA from LOW to HIGH while SCL is HIGH. The TMP512/13 includes a 28ms timeout on its interface R/\overline{W} bit LOW. Every write operation to the to prevent locking up an SMBus. TMP512/13 requires a value for the register pointer.

must first address slave devices via a slave address acknowledge receipt of a valid address. The next
byte. The slave address byte consists of seven byte transmitted by the master is the address of the byte. The slave address byte consists of seven byte transmitted by the master is the address of the address of the
address bits, and a direction bit indicating the intent register to which data will be written. This regist address bits, and a direction bit indicating the intent

The TMP512/13 feature an address pin to allow up to
four devices to be addressed on a single bus. [Table](#page-15-0) 1
describes the pin logic levels used to properly
The master may terminate data transfer by connect up to four devices. The state of the A0 pin is generating a START or STOP condition.
sampled on every bus communication and should be
set before any activity on the interface occurs. The When reading from the TMP51 set before any activity on the interface occurs. The University When reading from the TMP512/13, the last value
address unit is read at the start of each stored in the register pointer by a write operation address pin is read at the start of each communication event. determines which register is read during a read

DEVICE TWO-WIRE ADDRESS	AO PIN CONNECTION
1011100	Ground
1011101	V+
1011110	SDA
1011111	SCI.

The TMP512/13 operate only as slave devices on the byte. The master may terminate data transfer by two-wire bus and SMBus. SCL is an input only, and generating a Not-Acknowledge after receiving any TMP512/13 cannot drive it. Connections to the bus data byte, or generating a START or STOP condition. are made via the open-drain I/O lines SDA and SCL. If repeated reads from the same register are desired, The SDA and SCL pins feature integrated spike it is not necessary to continually send the register suppression filters and Schmitt triggers to minimize pointer bytes; the TMP512/13 retain the register the effects of input spikes and bus noise. The pointer value until it is changed by the next write TMP512/13 support the transmission protocol for fast operation. (1kHz to 400kHz) and high-speed (1kHz to 3.4MHz) $\frac{1}{24}$ and [Figure](#page-16-1) 25 show read and write modes. All data bytes are transmitted MSB first. $\frac{1}{24}$ and Figure 25 show read and write

HIGH. Any change in SDA while SCL is HIGH is
interpreted as a START or STOP condition.
interpreted as a START or STOP condition.

SERIAL BUS ADDRESS Writing to a register begins with the first byte **SERIAL BUS ADDRESS** transmitted by the master. This byte is the slave To communicate with the TMP512/13, the master address, with the R/W bit LOW. The TMP512/13 then must first address slave devices via a slave address acknowledge receipt of a valid address. The next of executing a read or write operation.
 $\frac{1}{2}$ address value updates the register pointer to the desired register. The next two bytes are written to the

operation. To change the register pointer for a read **Table 1. TMP512/13 Address Pins and** operation, a new value must be written to the register **Slave Addresses** pointer. This write is accomplished by issuing a slave pointer. This write is accomplished by issuing a slave address byte with the R/W bit LOW, followed by the register pointer byte. No additional data are required. The master then generates a START condition and sends the slave address byte with the R/W bit HIGH to initiate the read command. The next byte is transmitted by the slave and is the most significant byte of the register indicated by the register pointer. This byte is followed by an Acknowledge from the **SERIAL INTERFACE SERIAL INTERFACE SERIAL INTERFACE byte.** The master acknowledges receipt of the data

> register bytes are sent most-significant byte first, followed by the least significant byte. See [Figure](#page-17-1) 27 for an illustration of a typical register pointer configuration.

NSTRUMENTS

Texas

Figure 26. Timing Diagram for SMBus ALERT

Figure 27. Typical Register Pointer Set

[Figure](#page-18-0) 28 describes the timing operations on the

TMP512/13. Parameters for Figure 28 are defined in
 [Table](#page-18-1) 2. Bus definitions are:

Table 2. Bus definitions are:

Start Data Transfer: A change in the state of the bit. A device that acknowledges must pull down the SDA line, from high to low, while the SCL line is high, SDA line during the Acknowledge clock pulse in such SDA line, from high to low, while the SCL line is high, SDA line during the Acknowledge clock pulse in such such
defines a START condition. Each data transfer a way that the SDA line is stable low during the high defines a START condition. Each data transfer a way that the SDA line is stable low during the high

initiates with a START condition. Denoted as S in eperiod of the Acknowledge clock pulse. Setup and initiates with a START condition. Denoted as S in

Stop Data Transfer: A change in the state of the
SDA line from low to high while the SCL line is high
defines a STOP condition. Each data transfer
defines a STOP condition. Each data transfer terminates with a repeated START or STOP condition. Denoted as P in [Figure](#page-18-0) 28.

TIMING DIAGRAMS Data Transfer: The number of data bytes transferred
 Data Transfer: The number of data bytes transferred

Acknowledge: Each receiving device, when **Bus Idle:** Both SDA and SCL lines remain high.
addressed, is obliged to generate an Acknowledge [Figure](#page-18-0) 28. hold times must be taken into account. On a master
receive, data transfer termination can be signaled by

Figure 28. Two-Wire Timing Diagram

(1) For cases with fall time of SCL less than 20ns and/or the rise or fall time of SDA less than 20ns, the hold time should be greater than 20ns.

(2) For cases with a fall time of SCL less than 10ns and/or the rise or fall time of SDA less than 10ns, the hold time should be greater than 10ns.

HIGH-SPEED MODE SENSOR FAULT

above 400kHz, the master device must issue a Short-circuit conditions return a value of –256°C. The High-Speed mode (Hs-mode) master code (0000 detection circuitry consists of a voltage comparator 1xxx) as the first byte after a START condition to that trips when the voltage at DXP exceeds $(V+)$ – switch the bus to high-speed operation. The 0.6V (typical). The comparator output is continuously switch the bus to high-speed operation. The TMP512/13 do not acknowledge this byte, but switch checked during a conversion. If a fault is detected, the input filters on SDA and SCL and the output filter the OPEN bit (bit 0) in the temperature result register on SDA to operate in Hs-mode, allowing transfers at is set to '1' and the rest of the register bits should be up to 3.4MHz. After the Hs-mode master code has ignored. been issued, the master transmits a START condition
to a two-wire slave address that initiates a data
transfer operation. The bus continues to operate in
Hs-mode until a STOP condition occurs on the bus.
Upon receiving the switch the input and output filters back to Fast mode **UNDERVOLTAGE LOCKOUT** operation.

power supply (V+) exceeds 2.7V (typical). The two-wire bus General Call Reset. At device power up, comparator output is continuously checked during ^a all Status bits are masked, and the SMBus Alert comparator butput is continuously criecked during a
function is disabled. All watchdog outputs default to
emperature conversion if the power supply is not

the user flexibility to shut down the shunt/bus voltage measurement and the temperature measurement
functions individually.

To shut down the shunt/bus voltage measurement The TMP512/13 average the input diode voltages function immediately, set bits 2 through 0 in that determine the remote temperature by sampling
Configuration Register 1 (00h) to '000' respectively. multiple times throughout a conversion. The Configuration Register 1 (00h) to '000' respectively. multiple times throughout a conversion. The
To shut down the shunt/bus voltage measurement temperature result can be extracted from four To shut down the shunt/bus voltage measurement after the end of the current conversion, set bits 2 different V_{BE} readings and is sampled 600 times in through 0 in Configuration Resister 1 (00h) to '100' 130ms (max). Each V_{BE} voltage is sampled 150 times through 0 in Configuration Resister 1 (00h) to '100' 130ms (max). Each V_{BE} voltage is sampled 150 times respectively.

through integration capacitors that average the

To shut down the temperature measurement function
immediately, set bits 15 through 11 in Configuration
Register 2 (01h) to '00000' respectively. To shut
down the temperature measurement after the end of
the current conver

FILTERING ONE-SHOT COMMAND

shutuowin and the voltage core is in the subsection of the state on all enabled channels
by writing a '1' to the OS bit in Configuration Register
1. This write operation starts one conversion; the
1. This write operation s

In order for the two-wire bus to operate at frequencies The TMP512/13 can sense an open circuit. the OPEN bit (bit 0) in the temperature result register

The TMP512/13 sense when the power-supply **POWER-UP CONDITIONS** voltage has reached a minimum voltage level for the Power-up conditions apply to a software reset via the ADC to function. The detection circuitry consists of a
RST bit (bit 15) in the Configuration Register, or the voltage comparator that enables the ADC after the power su active low and transparent (non-latched) modes.
valid. The PVLD bit (see Status [Register](#page-36-0); Local
Temperature Reset Register; Remote Temperature **SHUTDOWN MODE** Reset Reset Register; Remote Temperature Temperature Reset Registers and 3 Registers) of the individual The TMP512/13 shutdown mode of operation allows Local/Remote Temperature Result Registers are set the user flexibility to shut down the shunt/bus voltage to '1' and the temperature result may be incorrect.

TEMPERATURE AVERAGING

through integration capacitors that average the

For the TMP512/13, when the temperature core is in

shutdown and the voltage core is in triggered mode, a

shutdown and the voltage core is in triggered mode, a

shutdown and the voltage core is in triggered mode, a

shutd 1. This write operation starts one conversion; the
TMP512/13 returns to shutdown mode when that
conversion completes. At the end of the conversion,
the Conversion Ready flags (bit 6 and bit 5) in the
Status Register are se coupled signals. The value of this capacitor should be

between 100pF and 1nF. Some applications attain Where: better overall accuracy with additional series $n =$ ideality factor of remote temperature sensor. resistance; however, this increased accuracy is
application-specific. When series resistance is added,
the total value should not be greater than 3kO If $T_{\text{ERR}} =$ error in TMP512/13 because n \neq 1.008. TERR = error in TMP512/13 because n ≠ the total value should not be greater than $3k\Omega$. If the serve that in TMP512/13 because n ≠ 1.008. The total value should not be greater than $3k\Omega$. If the same for ∞ and K. filtering is needed, suggested component values are 100pF and 50Ω on each input; exact values are For n = 1.004 and T(°C) = 100°C: application-specific.

GENERAL CALL RESET

The TMP512/13 support reset via the two-wire General Call address 00h (0000 0000b). The $I_{\text{ERR}} = 1.48^{\circ}\text{C}$ (5) TMP512/13 acknowledge the General Call address
and respond to the second byte. If the second byte is
06h (0000 0110b), the TMP512/13 execute a
software reset state to all TMP512/13 registers and
software reset state to all software reset state to all TMP512/13 registers, and
abort any conversion in progress. The TMP512/13 according to the following criteria:
take no action in response to other values in the 1. Base-emitter voltage > 0.25V at take no action in response to other values in the second byte. **highest sensed temperature.** highest sensed temperature.

The TMP512/13 are designed to be used with either $\qquad 3.$ Base resistance < 100 $\Omega.$ discrete transistors or substrate transistors built into 4. Tight control of V_{BE} characteristics indicated by processor chips and ASICs. Either NPN or PNP small variations in h_{FE} (that is, 50 to 150). processor chips and ASICs. Either NPN or PNP transistors can be used, as long as the base-emitter junction is used as the remote temperature sense.

NPN transistors must be diode-connected. PNP small-signal transistors are the 2N3904 (NPN) or

transistors can either be transistor- or 2N3906 (PNP). diode-connected, as [Figure](#page-11-0) ¹⁹ and [Figure](#page-11-1) ²¹ show. **BASIC ADC FUNCTIONS**

Errors in remote temperature sensor readings are typically the consequence of the ideality factor and The two analog inputs to the $TMP512/13$, V_{IN+} and typically the consequence of the ideality factor and current excitation used by the TMP512/13 versus the V_{IN} , connect to a shunt resistor in the bus of interest. current excitation used by the TMP512/13 versus the V_{IN}, connect to a shunt resistor in the bus of internal manufacturer-specified operating current for a given The TMP512/13 are powered by an internal represents specify transistor. Some manufacturers specify a high-level subregulator, which has a typical output of 3.3V. The
and low-level current for the temperature-sensing bus being sensed can vary from 0V to 26V. There are and low-level current for the temperature-sensing bus being sensed can vary from 0V to 26V. There are
substrate transistors. The TMP512/13 use 6uA for the special considerations for power-supply substrate transistors. The TMP512/13 use 6μA for I_{low} and 120µA for I_{HGH} .

The ideality factor (n) is a measured characteristic of The TMP512/13 sense the small drop across the a remote temperature sensor diode as compared to shunt for shunt voltage, and sense the voltage with an ideal diode. The TMP512/13 allow for different respect to ground from V_{IN} for the bus volt n-factor values; see the *n-Factor Correction Register* Figure 29 for an illustration of this operation. n-factor values; see the *n-Factor [Correction](#page-14-4) Register* section.

The ideality factor for the TMP512/13 is trimmed to mode (that is, MODE bits of Configuration Register 1 be 1.008. For transistors that have an ideality factor are set to '111'), the devices continuously convert the that does not match the TMP512/13, [Equation](#page-20-0) 4 can shunt voltage up to the number set in the shunt be used to calculate the temperature error. Note that voltage averaging function (Configuration Register 1) be used to calculate the temperature error. Note that voltage averaging function (Configuration Register 1, for the equation to be used correctly, actual SADC bits). The devices then convert the bus voltage for the equation to be used correctly, actual SADC bits). The devices then convert the bus voltage femperature (°C) must be converted to kelvins (K).

$$
T_{\text{ERR}} = \left(\frac{n - 1.008}{1.008}\right) \times \left(273.15 + T(^{\circ}\text{C})\right)
$$
(4)

$$
T_{\text{ERR}} = \left(\frac{1.004 - 1.008}{1.008}\right) \times \left(273.15 + 100^{\circ}\text{C}\right)
$$

 $T_{\text{evo}} = 1.48$ °C

-
- 2. Base-emitter voltage < 0.95V at 120μA, at the **REMOTE SENSING SENSING** *CONSING CONSING C*
	-
	-

present with the supply voltage off, and vice-versa). respect to ground from V_{IN-} for the bus voltage. See

When the TMP512/13 are in the normal operating are set to '111'), the devices continuously convert the up to the number set in the bus voltage averaging (Configuration Register 1, BADC bits). The Mode control in Configuration Register 1 also permits (4) selecting modes to convert only voltage or current, either continuously or in response to a two-wire space command.

Figure 29. TMP512/13 Configured for Shunt and Bus Voltage Measurement

All current and power calculations are performed in
the background and do not contribute to conversion
time; conversion times shown in the [Electrical](#page-3-0)
[Characteristics](#page-3-0) table can be used to determine the
Register or triggerin actual conversion time.
POWER MEASUREMENT
Power-Down mode reduces the quiescent current

Power-Down mode reduces the quiescent current
and turns off current into the TMP512/13 inputs,
avoiding any supply drain. Full recovery from points in time, depending on the resolution and
Power-Down requires 40µs. ADC Off

Although the TMP512/13 can be read at any time, the background and do not add to the overall and the data from the last conversion remain conversion time. available, the Conversion Ready bit and the Conversion Ready Temperature bit (Status Register, **PGA FUNCTION** CVR and CRT) are provided to help co-ordinate If larger full-scale shunt voltages are desired, the conversions. The Conversion
Ready bit and the Conversion Ready Temperature bit
Ready bit and the Conversion Ready Temperature bit Ready bit and the Conversion Ready Temperature bit IMP512/13 provide a PGA function that increases are set after all conversions averaging and the full-scale range up to 2, 4, or 8 times (320mV). are set after all conversions, averaging, and multiplication operations are complete. Additionally, the bus voltage measurement has two multiplication operations are complete.

full-scale ranges: 16V or 32V.

the TNP312/13 full-scale large of 4000 enables the
limit. When sensing is required at (or through) the
50mV sense point of the TPS2490, the PGA of the
TMP512/13 can be set to \div 2 to provide an 80mV full-scale range. Overload conditions are another consideration for the

averaging in Configuration Register 1. These littering
options can be set independently for either voltage or
could avecad the 26V differential and segment media

The internal ADC is based on a delta-sigma (ΔΣ)

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COMPATIBILITY WITH TI HOT-SWAP This architecture has good inherent noise rejection;
 CONTROLLERS The only only the property of the property in the contract of the head of very close to the however, transients that occur at or very close to the sampling rate harmonics can cause problems. The TMP512/13 are designed for compatibility with
hot-swap controllers such the TI [TPS2490.](http://focus.ti.com/docs/prod/folders/print/tps2490.html) The
TPS2490 uses a high-side shunt with a limit at 50mV;
the TMP512/13 full-scale range of 40mV enables the
use of low-value serie

TMP512/13 inputs. The TMP512/13 inputs are **FILTERING AND INPUT CONSIDERATIONS** specified to tolerate 26V across the inputs. A large differential scenario might be a short to ground on the Measuring current is often noisy, and such noise can
be differential scenario might be a short to ground on the
be difficult to define. The TMP512/13 offer several
options for filtering by choosing resolution and
averaging could exceed the 26V differential and common-mode rating of the TMP512/13. Inductive kickback voltages front-end with a 500kHz (±10%) typical sampling rate. are best dealt with by zener-type transient-absorbing devices (commonly called transzorbs) combined with sufficient energy storage capacitance.

Figure 30. TMP512/13 with Input Filtering

In applications that do not have large energy storage not generate an Acknowledge and continues to hold electrolytics on one or both sides of the shunt, an the ALERT line low until the interrupt is cleared. input overstress condition may result from an Successful completion of the read alert response excessive dV/dt of the voltage applied to the input. A protocol clears the SMBus ALERT pin, provided that hard physical short is the most likely cause of this the condition causing the alert no longer exists. The event, particularly in applications with no large SMBus Alert flag is cleared separately by either electrolytics present. This problem occurs because an reading the Status Register or by disabling the excessive dV/dt can activate the ESD protection in SMBus Alert function. excessive dV/dt can activate the ESD protection in the TMP512/13 in systems where large currents are
available. Testing has demonstrated that the addition
of 10Ω resistors in series with each input of the watchdogs have been activated. After power-on
TMP512/13 sufficientl These resistors have no significant effect on **EXTERNAL CIRCUITRY FOR ADDITIONAL**
VBUS INPUT

The SMBus alert response functions only when the
Alert pin is active and in latch mode (03h, bit $0 = 1$);
see [Figure](#page-17-0) 26. The ALERT interrupt output signal is
latched and can be cleared only by either reading the
Status Re alert response address. If the fault is still present, the Consideration must be given to the typical 20μA input
ALERT pin re-asserts. Asserting the ALERT pin does current of each TMP512/13 input, along with the not halt automatic conversions that are already in progress. The ALERT output pin is open-drain, progress. The ALERT output pin is open-drain, bus voltage is measured. These effects can create allowing multiple devices to share a common interrupt errors through the resistance of any external allowing multiple devices to share a common interrupt errors through the resistance of any external
line switching method used. The excist way to avoid

The TMP512/13 respond to the SMBus alert minimum; select switching MOSFETs with the lowest response address, an interrupt pointer return-address possible $R_{DS(on)}$ values. provides quick fault identification for simple slave The circuit shown in [Figure](#page-24-0) 31 uses MOSFET pairs to devices. When an ALERT occurs, the master can reduce package count. Back-to-back MOSFETs must
broadcast the alert response slave address (0001 be used in each leg because of the built-in back 100). Following this alert response, any slave devices diodes from source-to-drain. In this circuit, the normal that generated interrupts identify themselves by putting the respective addresses on the bus.

FET. The alert response can activate several different slave devices simultaneously, similar to the two-wire General Call. If more than one slave attempts to respond, bus arbitration rules apply; the device with the lower address code wins. The losing device does

SMBus ALERT RESPONSE The TMP512/13 GPIO can be used to control an

current of each TMP512/13 input, along with the 320k Ω impedance present at the V_{IN} input where the switching method used. The easiest way to avoid these errors is by reducing this resistance to a

be used in each leg because of the built-in back connection for V_{IN-} is at the shunt, with the optional voltage measurement at the output of the control

Figure 31. External Circuitry for Additional V_{BUS} Input

PROGRAMMING THE TMP512/13 POWER MEASUREMENT ENGINE

Calibration Register and Scaling

The Calibration Register makes it possible to set the scaling of the Current and Power Registers to whatever values are most useful for a given application. One strategy may be to set the Calibration Register such that the largest possible number is generated in the Current Register or Power Register at the expected full-scale point; this approach yields the highest resolution. The Calibration Register can also be selected to provide values in the Current and Power Registers that either provide direct decimal equivalents of the values being measured, or yield a round LSB number. After these choices have been made, the Calibration Register also offers possibilities for end user system-level calibration, where the value is adjusted slightly to cancel total system error.

This section presents two examples for configuring the TMP512/13 calibration. Both examples are written so the information relates directly to the calibration setup found in the TMP512/13EVM software.

Calibration Example 1: Calibrating the TMP512/13 with no possibility for overflow.

NOTE

The numbers used in this example are the same used with the TMP512/13EVM software as shown in [Figure](#page-27-0) 32.

1. Establish the following parameters:

$$
V_{\text{BUS_MAX}} = 32
$$

 V_{SHUNT} MAX = 0.32

 $R_{SHUNT} = 0.5$

2. Use [Equation](#page-25-0) 6 to determine the maximum possible current .

$$
MaxPossible_l = \frac{V_{shUNT_MAX}}{R_{shunT}}
$$

MaxPossible l = 0.64

3. Choose the desired maximum current value. This value is selected based on system expectations.

 $Max_Expected_l = 0.6$

4. Calculate the possible range of current LSBs. To calculate this range, first compute a range of LSBs that is appropriate for the design. Next, select an LSB within this range. Note that the results will have the most resolution when the minimum LSB is selected. Typically, an LSB is selected to be the nearest round number to the minimum LSB value.

Minimum_LSB =
$$
\frac{\text{Max_Expected_I}}{32767}
$$

\nMinimum_LSB =
$$
18.311 \times 10^{-6}
$$

\nMaximum_LSB =
$$
\frac{\text{Max_Expected_I}}{4095}
$$

Maximum_LSB = 146.520×10^{-6}

Choose an LSB in the range: Minimum_LSB < Selected_LSB < Maximum_LSB

Current_LSB = 20×10^{-6}

Note:

This value was selected to be a round number near the Minimum_LSB. This selection allows for good resolution with a rounded LSB.

5. Compute the Calibration Register value using [Equation](#page-25-1) 9:

$$
Cal = trunc \left[\frac{0.04096}{Current_LSB \times R_{SHUNT}} \right]
$$

 $Cal = 4096$

(7)

(6)

(8)

(9)

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Corrected_Full_Scale_Cal = trunc Cal × MeasShuntCurrent TMP513_Current Corrected_Full_Scale_Cal = 3548

 (14)

[Figure](#page-27-0) 32 illustrates how to perform the same procedure discussed in this example using the automated TMP512/13EVM software. Note that the same numbers used in this nine-step example are used in the software example. Note also that [Figure](#page-27-0) 32 illustrates which results correspond to which step (for example, the information entered in Step 1 is enclosed in a box in [Figure](#page-27-0) 32 and labeled).

 $\overline{\mathsf{x}}$

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Figure 32. TMP512/513EVM Calibration Software Automatically Computes Calibration Steps 1-9

Calibration Example 2 (Overflow Possible)

This design example uses the nine-step procedure for calibrating the TMP512/13 where overflow is possible. [Figure](#page-30-0) 33 illustrates how the same procedure is performed using the automated TMP512/13EVN software. The same numbers used in the nine-step example are used in the software example shown in [Figure](#page-30-0) 33. Note also that [Figure](#page-30-0) 33 illustrates which results correspond to which step (for example, the information entered in Step 1 is circled in [Figure](#page-30-0) 33 and labeled).

1. Establish the following parameters:

 $V_{BUS_MAX} = 32$

 V_{SHUNT} MAX = 0.32

 $R_{\text{SHUNT}} = 5$

2. Determine the maximum possible current using [Equation](#page-28-0) 15:

$$
MaxPossible_l = \frac{V_{SHUNT_MAX}}{R_{SHUNT}}
$$

MaxPossible l = 0.064

(15)

(17)

3. Choose the desired maximum current value: Max_Expected_I, ≤ MaxPossible_I. This value is selected based on system expectations.

Max_Expected_I = 0.06

4. Calculate the possible range of current LSBs. This calculation is done by first computing a range of LSB's that is appropriate for the design. Next, select an LSB withing this range. Note that the results will have the most resolution when the minimum LSB is selected. Typically, an LSB is selected to be the nearest round number to the minimum LSB.

Minimum_LSB =
$$
\frac{\text{Max_Expected_I}}{32767}
$$

\nMinimum_LSB = 1.831×10^{-6} (16)

\nMaximum_LSB = $\frac{\text{Max_Expected_I}}{4095}$

\nMaximum_LSB = 14.652×10^{-6} (17)

Choose an LSB in the range: Minimum_LSB < Selected_LSB < Maximum_LSB

Current LSB = 1.9×10^{-6}

Note:

This value was selected to be a round number near the Minimum_LSB. This section allows for good resolution with a rounded LSB.

5. Compute the calibration register using [Equation](#page-28-1) 18:

$$
Cal = trunc \left[\frac{0.04096}{Current_LSB \times R_{shUNT}} \right] \quad Cal = 4311
$$

6. Calculate the Power LSB using [Equation](#page-28-2) 19. [Equation](#page-28-2) 19 shows a general formula; because the bus voltage measurement LSB is always 4mV, the power formula reduces to calculate the result.

Power_LSB = 20 Current_LSB

Power_LSB = 38×10^{-6}

(19)

(18)

[TMP512](http://focus.ti.com/docs/prod/folders/print/tmp512.html) [TMP513](http://focus.ti.com/docs/prod/folders/print/tmp513.html)

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MeaShuntCurrent = 0.05

$$
Corrected_Full_Scale_Cal = trunc \left(\frac{Cal \times MeasShuntCurrent}{TMP513_Current} \right)
$$

Corrected_Full_Scale_Cal = 3462

(23)

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Figure 33. TMP512/513EVM Calibration Software Automatically Computes Calibration Steps 1-9

REGISTER INFORMATION

The TMP512/13 uses a bank of registers for holding the write command. Therefore, a 4μs delay is configuration settings, measurement results, required between the completion of a write to a given maximum/minimum limits, and status information. register and a subsequent read of that register Table 3 summarizes the TMP512/13 registers. (without changing the pointer) when using SCL Register contents are updated 4µs after completion of

(without changing the pointer) when using SCL frequencies in excess of 1MHz.

(1) Type: $R = Read-Only$, $R/\sqrt{W} = Read/W$ rite.

(2) Current Register defaults to '0' because the Calibration Register defaults to '0', yielding a zero current value until the Calibration Register is programmed.

(3) For TMP513 only.

Table 3. Summary of Register Set (continued)

(4) For TMP513 only.

REGISTER DETAILS

All TMP512/13 registers are 16-bit registers. 16-bit register data are sent in two 8-bit bytes via the two-wire interface.

Bit Descriptions

Table 4. PG Bit Settings(1)

(1) Shaded values are default.

BADC: BADC Bus ADC Resolution/Averaging

Bits 10–7 These bits adjust the Bus ADC resolution (9-, 10-, 11-, or 12-bit) or set the number of samples used when averaging results for the Bus Voltage Register (05h).

SADC: SADC Shunt ADC Resolution/Averaging

Bits 6–3 These bits adjust the Shunt ADC resolution (9-, 10-, 11-, or 12-bit) or set the number of samples used when averaging results for the Shunt Voltage Register (04h).

BADC (Bus) and SADC (Shunt) ADC resolution/averaging and conversion time settings are shown in [Table](#page-33-1) 5.

Table 5. ADC Settings(1)

(1) Shaded values are default.
(2) $X = Don't care$.

 $X =$ Don't care.

MODE: Operating Mode

Bits 2–0 Selects continuous, triggered, or power-down mode of operation. These bits default to continuous shunt and bus measurement mode. The mode settings are shown in [Table](#page-33-2) 6.

Table 6. Mode Settings(1)

(1) Shaded values are default.

(2) Combination '000' stops converter immediately.

(3) In triggered modes the converter goes to power down. It can be triggered by a write of '1' to bit 14 (One-Shot) in Configuration Register 1 or by the delay scheme of the temperature sensor core. See [Table](#page-34-0) 7.

(4) Combination '100' stops the converter at conversion end.

RC: Resistance Correction

- Bit 10 0: Resistance correction disabled.
	- 1: Resistance correction enabled.

R2, R1, R0: Conversion Rate

Table 7. Conversion Rate Settings(1)

(1) Shaded values are default.

(2) Conversion rate shown is for only one or two enabled measurement channels. When three channels are enabled, the conversion rate is 2 and 2/3 conversions per second. When four channels are enabled, the conversion rate is 2 per second.

(3) Conversion rate shown is for only one enabled measurement channel. When two channels are enabled, the conversion rate is 4 conversions per second. When three channels are enabled, the conversion rate is 2 and 2/3 conversions per second.

When all of the following conditions are met, the temperature sensor core triggers a single conversion of the voltage measurement core at the same rate as the conversion rate shown by bits R2 to R0.

- The conversion rate is different than '111';
- There is at least one enabled temperature channel; and
- The voltage measurement core is in triggered mode of operation.

The temperature sensor core triggers a single conversion of the ADC core at the same rate as the conversion rate shown by R2 to R0.

- **GP: GPIO Read-Back**
- Bit 2 Shows the state of the GPIO pin.
- **GPM: GPIO Mode**

Bits 1-0 The GPIO mode settings are shown in [Table](#page-35-0) 8. GPIO should not be left floating at start-up.

Table 8. GPIO Mode Settings(1)

(1) Shaded values are default.

Status Register 02h (Read)

The Status Register flags activate whenever any limit is violated, and latch if the alert is in latch mode. In latch mode, these flags are cleared when the Status Register is read (if the limit is exceeded, then at next conversion end, the flag sets again). In transparent mode, these flags are cleared when any corresponding limit is not violated any longer.

After power-up and initial setup, the Status Register should be read once to clear any flags set as a result of power-up values prior to setup.

Bit Descriptions

Bits D4–D15 of the SMBus Alert Register mask correspond to bits D4 to D15 of the Status Register to prevent them from initiating an SMBus Alert. It does not prevent the Status Register bit from setting. Writing a '0' to an SMBus Alert Mask bit masks it from activating the SMBus Alert. All default values are '0'.

Bit Descriptions

1: Alert pin works in latch mode. The SMB alert response function functions when Alert pin is active. Alert will remain asserted even if the triggering condition goes away. Alert can be deasserted by reading the Status register (02h), using the SMBus Alert response function, resetting the part, or by disabling the alert function using the mask bits.

Shunt Voltage Register 04h (Read-Only)

The Shunt Voltage Register stores the current shunt voltage reading, V_{SHUNT}. Shunt Voltage Register bits are shifted according to the PGA setting selected in Configuration Register 1 (00h). When multiple sign bits are present, they will all be the same value. Negative numbers are represented in twos complement format. Generate the twos complement of a negative number by complementing the absolute value binary number and adding 1. Extend the sign, denoting a negative number by setting the MSB = '1'. Extend the sign to any additional sign bits to form the 16-bit word.

Example: For a value of $V_{\text{SHUNT}} = -320 \text{mV}$:

- 1. Take the absolute value (include accuracy to 0.01mV)==> 320.00
- 2. Translate this number to a whole decimal number ==> 32000
- 3. Convert it to binary==> 111 1101 0000 0000
- 4. Complement the binary result : 000 0010 1111 1111
- 5. Add 1 to the Complement to create the twos complement formatted result ==> 000 0011 0000 0000
- 6. Extend the sign and create the 16-bit word: 1000 0011 0000 0000 = 8300h (Remember to extend the sign to all sign-bits, as necessary based on the PGA setting.)

At PGA = \div 8, full-scale range = ± 320 mV (decimal = 32000, positive value hex = 7D00, negative value hex = 8300), and $LSB = 10 \mu V$.

At PGA = $\div 4$, full-scale range = ± 160 mV (decimal = 16000, positive value hex = 3E80, negative value hex = C180), and $LSB = 10\mu V$.

BIT#	D ₁₅	D ₁₄	D ₁₃	D ₁₂	D11	D ₁₀	D9	D ₈	D7	D6	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀
BIT NAME	SIGN	SIGN	SD13_4	SD12_4	SD _{11_4}	SD _{10_4}	SD9_4	SD8_4	SD7_4	SD6_4	SD5_4	SD4_4	SD3_4	SD2_4	SD1_4	$SD0_4$
POR VALUE																

At PGA = \div 2, full-scale range = \pm 80mV (decimal = 8000, positive value hex = 1F40, negative value hex = E0C0), and $LSB = 10\mu V$.

At PGA = \div 1, full-scale range = \pm 40mV (decimal = 4000, positive value hex = 0FA0, negative value hex = F060), and $LSB = 10\mu V$.

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Table 9. Shunt Voltage Register Format(1)

(1) Out-of-range values are shaded.

Bus Voltage Register 05h (Read-Only)

The Bus Voltage Register stores the most recent bus voltage reading, V_{BUS} .

At full-scale range = $32V$ (decimal = 8000 , hex = $1F40$), and LSB = $4mV$.

At full-scale range = $16V$ (decimal = 4000 , hex = $0FA0$), and LSB = $4mV$.

Power Register 06h (Read-Only)

Full-scale range and LSB are set by the Calibration Register. See the *[Programming](#page-25-2) the TMP512/13 Power* [Measurement](#page-25-2) Engine section.

The Power Register records power in watts by multiplying the values of the current with the value of the bus voltage according to the equation:

$$
Power = \frac{Current \times BusVoltage}{}
$$

5000

Current Register 07h (Read-Only)

Full-scale range and LSB depend on the value entered in the Calibration Register. See the *[Programming](#page-25-2) the* TMP512/13 Power [Measurement](#page-25-2) Engine section. Negative values are stored in twos complement format.

The value of the Current Register is calculated by multiplying the value in the Shunt Voltage Register with the value in the Calibration Register according to the equation:

Current $=$ $-$ ShuntVoltage \times Calibration Register 4096

Local Temperature Result Register 08h (Read-Only)

The data format is 13 bits, 0.0625° C per bit. Full-scale allows display up to $\pm 256^{\circ}$ C.

T12–**T0: Temperature Result**

Bits 15-3 Shows the temperature result according to the format shown in [Table](#page-43-1) 10.

Table 10. 13-Bit Temperature Data Format

For positive temperatures (for example, +50°C):

Twos complement is not performed on positive numbers. Therefore, simply convert the number to binary code with the 13-bit, left-justified format, and $MSB = 0$ to denote a positive sign.

Example: $(+50^{\circ}C)/(0.0625^{\circ}C/count) = 800 = 320h = 00110010000$

For negative temperatures (for example, –25°C):

Generate the twos complement of a negative number by complementing the absolute value binary number and adding 1. Denote a negative number with $MSB = 1$.

Example: $(-25^{\circ}C)/(0.0625^{\circ}C/count) = 400 = 190h = 0001 1001 0000$

Twos complement format: 1110 0110 1111 + 1 = 1110 0111 0000

PVLD Power Valid Flag Bit 1 This bit is the power valid flag. The TMP512/13 do not start a temperature conversion if the power supply is not valid. If the voltage is less than 2.7V during a conversion, the PVLD bit is set to '1' and the temperature result may be incorrect.

Remote Temperature Result 1 Register 09h, Remote Temperature Result 2 Register 0Ah, Remote Temperature Result 3 Register (TMP513 Only) 0Bh (Read-Only)

The data format is 13 bits, 0.0625°C per bit. Full-scale allows display up to ±256°C.

Shunt Positive Limit Register 0Ch (Read/Write)

At full-scale range = ±320mV, 15-bit + sign, LSB = 10μV (decimal = 32000, positive value hex = 7D00, negative value hex = 8300).

Shunt Negative Limit Register 0Dh (Read/Write)

At full-scale range = ± 320 mV (decimal = 32000, positive value hex = 7D00, negative value hex = 8300). 15 bit + sign, $LSB = 10\mu\text{V}$.

Bus Voltage Positive Limit Register 0Eh (Read/Write)

At full-scale range = $32V$ (decimal = 8000, hex = 1F40), and LSB = $4mV$.

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Bus Voltage Negative Limit Register 0Fh (Read/Write)

At full-scale range = $32V$ (decimal = 8000 , hex = $1F40$), and LSB = $4mV$. **BIT # D15 D14 D13 D12 D11 D10 D9 D8 D7 D6 D5 D4 D3 D2 D1 D0**

Power Limit Register 10h (Read/Write)

At full-scale range, same as the Power Register (06h).

Local Temperature Limit Register 11h, Remote Temperature Limit 1 Register 12h, Remote Temperature Limit 2 Register 13h, Remote Temperature Limit 3 Register 14h (TMP513 Only) (Read/Write)

The data format is 13 bits.

TH12–**TH0: Temperature Limit**

Bits 15-3 Shows the temperature limit.

Shunt Calibration Register 15h (Read/Write)

Current and power calibration are set in the Calibration Register. Note that bit D0 is not used in the calculation. This register sets the current that corresponds to a full-scale drop across the shunt. Full-scale range and the LSB of the current and power measurement depend on the value entered in this register. See the [Programming](#page-25-2) the TMP512/13 Power [Measurement](#page-25-2) Engine section. This register is suitable for use in overall system calibration. Note that the '0' POR values are all default.

(1) D0 is a void bit and is always '0'. It is not possible to write a '1' to D0.

n-Factor 1 Register 16h (Read/Write)

NF7–**NF0: n-Factor Bits**

Bits 15-8 Shows the n-factor for Channel 1 according to the range indicated in [Table](#page-46-0) 11.

Table 11. n-Factor Range(1)

(1) Shaded values are default.

HST7–**HST0: Hysteresis Register Bits**

Bits 7-0 The hysteresis register is binary coded. 1LSB is equal to 0.5°C, so the possible hysteresis range is 0°C to 127.5°C.

n-Factor 2 Register 17h (Read/Write)

NF7–**NF0: n-Factor Bits**

Bits 15-8 Shows the n-factor for Channel 2 according to the range indicated in [Table](#page-46-0) 11.

n-Factor 3 Register 18h (TMP513 Only) (Read/Write)

NF7–**NF0: n-Factor Bits**

Bits 15-8 Shows the n-factor for Channel 3 according to the range indicated in [Table](#page-46-0) 11.

Manufacturer ID Register 1Eh and FEh (Read-Only)

ID7–**ID0: Identification Register Bits**

Bits 15-8 These bits provide the manufacturer ID.

Device ID Register 1Fh and FFh (Read-Only)

DID7–**DID0: Identification Register Bits**

Bits 15-8 These bits provide the device ID.

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

PACKAGING INFORMATION

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

STRUMENTS

*All dimensions are nominal

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

PACKAGE OUTLINE

D0014A SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

D0014A SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.

 $D (R-PDSO-G16)$

PLASTIC SMALL OUTLINE

NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- 6 Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.

GENERIC PACKAGE VIEW

RSA 16 VQFN - 1 mm max height

4 x 4, 0.65 mm pitch PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

PACKAGE OUTLINE

RSA0016B VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
- 4. Reference JEDEC registration MO-220.

EXAMPLE BOARD LAYOUT

RSA0016B VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

NOTES: (continued)

5. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

6. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RSA0016B VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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